



WP5 PDK Support and 2.5/3D Tools

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GF 130 LP

- Available Now
- 300mm
- 8 1X metals
- MIM Cap
- LVT, RVT, ZVT
- 1.5V core
- 1.5/2.5/3.3V I/O
- Full PDK with Artisan Libraries
- 1.2um x 6um Tungsten TSV middle

GF 65 LP

- Available Now
- 300mm
- 4-6 1X metals
- 1-3 2X metals
- 1-2 4X metals
- VNat Cap
- e-FUSE
- SLVT, LVT, RVT, HVT, ZVT
- 1.5V core
- 1.5/2.5/3.3V I/O
- Full PDK June
- 1.2um x 6um Tungsten TSV middle*

GF 40 LP

- Available TBD
- 300mm
- 4-7 1X metals
- 1 2X metals
- 1-2 6X metals
- VNat Cap
- e-FUSE
- SLVT, LVT, RVT, HVT, ZVT
- 1.1/1.2V core
- 1.5/1.8/2.5/3.3 I/O
- 5V LDMOS
- PDK Only Tezzaron internal
- 1.2um x 6um Tungsten TSV middle*

GF 28 HPP

- Available TBD
- 300mm
- 4-6 1X metals
- 1-2 2X metals
- 1-2 6X metals
- 1-2 12X metals
- VNat Cap
- e-FUSE
- SLVT, LVT, RVT, HVT, ZVT
- 0.9/1.0V core
- 1.5/1.8/2.5/3.3V I/O
- PDK Only Tezzaron internal
- 1.2um x 6um Tungsten TSV middle*

IBM 90 LP

- Available Now
- 200mm
- 4 1X metals
- 4 2X metals
- LVT, RVT
- PDK Partial today, Full in March
- 1.2um x 8um Tungsten TSV
- Near end of TSV at 2X

IBM 90nm LP PDK

- Finalized Techfile for Virtuoso (Layout)
 - TSV's
 - Novati Copper DBI Processing
 - 2X Novati Metals
 - IBM FEOL and 1X Metals
- Finalized Techfile for Encounter (APR)
 - Capacitance Tables (.tch)
- Finalized Calibre DRC Rules
 - TSV's
 - Novati Copper DBI Processing
 - 2X Novati Metals
 - IBM FEOL and 1X Metals

IBM 90nm LP PDK

- Finalized LVS Rules
 - TSV's
 - Novati Copper DBI Processing
 - 2X Novati Metals
 - IBM FEOL and 1X Metals
- Finalized Calibre PEX rules
 - TSV's
 - Novati Copper DBI Processing
 - 2X Novati Metals
 - IBM FEOL and 1X Metals
- Spice Models
 - TSV's
 - Novati DBI Interconnects
- Electromigration Models or Current Density models for power rail analysis (Cadence Voltage Storm)

IBM 90nm LP PDK

- Capacitance Tables (*.CapTbl) for QRC
 - FuncCmax
 - FuncCmin
 - SigCmax
 - SigCmin
 - nm (nominal)
- Interconnect technology (*.ict) for Encounter and QRC
 - FuncCmax
 - FuncCmin
 - SigCmax
 - SigCmin
 - nm (nominal)
- Technology Routing (*.lef) for Encounter
 - Spacing
 - Widths
 - Capacitances
 - Resistances
 - Antenna ratio
 - Vias
 - Viarules (for array generation)
- Technology Files for Virtuoso
 - Technology Definition in ASCII (*.tf or *.asc)
 - Display (*.drf)
 - Layermap

SiCB 2K

- Available Now
- 200-300mm
- 1-4 2x2um metals
- 1-2 2x2um bottom metals
- 26x31.5mm reticle up to 2x2
- Trench Cap
- Full PDK March
- 10um x 100um Copper TSV middle

New Tool Support

- Cadence Virtuoso
 - 2 layer dual synchronized window
- MicroMagic
 - 3D Path finder
- Mentor ADIT/ELDO
 - 3D hooks